Wire pull

The principle behind basic wire bond testing is positioning of a hook underneath the wire and pulling in the Z axis either until the bond breaks (destructive testing) or a pre-defined force is reached (non-destructive testing).

Wire bond testing is covered by the external standard MIL-STD-883 (Methods 2011.7 for destructive testing and 2023.5 for non-destructive). Nordson DAGE bondtesters fully conform to or exceed these standards. The standards contain specifications for acceptance or rejection criteria.

Small geometry (Ultra Fine Pitch) applications are becoming more and more popular and as such Nordson DAGE offers wire pulling test equipment optimized specifically for this function.

A wire pull test can be performed manually or semi-automatically to a preprogrammed test routine.

Pull angle modeling is also available with DVS2811 software.